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DOCKET NO. : MERCHANT 33-3-3

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PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sailesh Merchant, *et al.*

Serial No.: 09/092,158

Filed: June 5, 1998

For: METHOD FOR THE FABRICATION OF CONTACTS IN AN INTEGRATED CIRCUIT DEVICE

Grp./A.U.: 2823

Examiner: Eaton, K.

Honorable Commissioner of Patents
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on 12/4/01 (Date)
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(Signature of the person signing the certificate)

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.111

In response to the Examiner's Action mailed September 4, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

(1) Kindly amend Claim 1 as follows:

1. (Three Times Amended) A process for fabricating a contact in a semiconductor substrate having a contact opening formed therein, comprising:

C/